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Lu et al.

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(54) **ELECTRONIC COMPONENT HEATSINK ASSEMBLY**

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(73) Assignee: **ADDA CORP.**, Kaohsiung (TW)

(**) Term: **15 Years**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179, 145, 184; D23/318, 322
CPC B60H 1/2206; B60H 1/00264; B60H 1/00357; F24H 1/009; F24H 1/06; H05K 7/20172; F28F 2215/00; F28F 2215/02; F28F 2250/00; F28F 3/022; F28F 2215/04; G06F 1/20; F21V 29/80; F21V 29/81; H01L 23/3677; F28D 2021/0029
See application file for complete search history.

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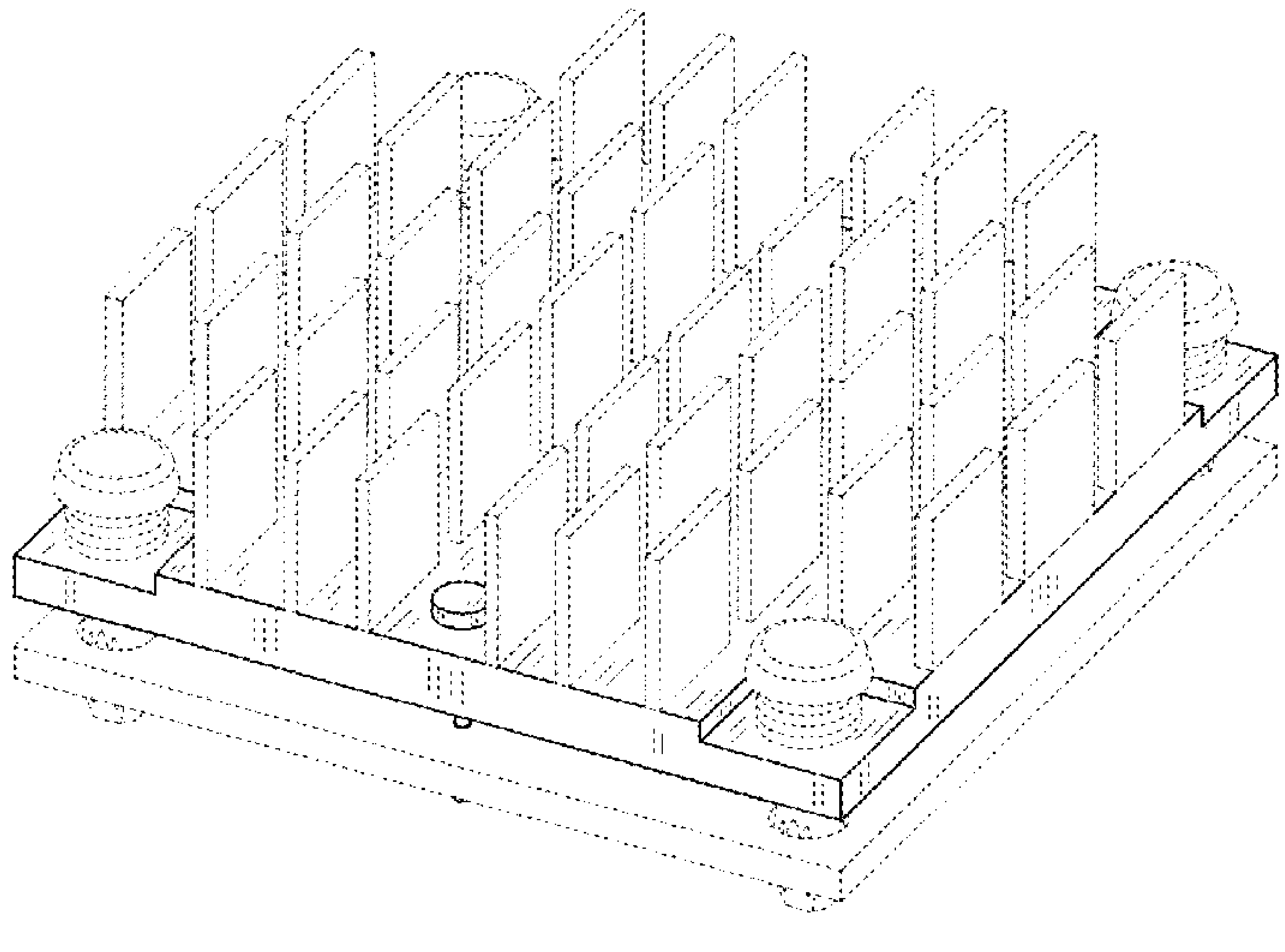
(57) **CLAIM**

The ornamental design for an electronic component heatsink assembly, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of an electronic component heatsink assembly showing our new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a right side elevational view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a rear elevational view thereof; and,
FIG. **7** is a bottom plan view thereof.
The broken lines showing of an electronic component, fins and push pins in the drawings depict environmental subject matter only and form no part of the claimed design.

1 Claim, 4 Drawing Sheets



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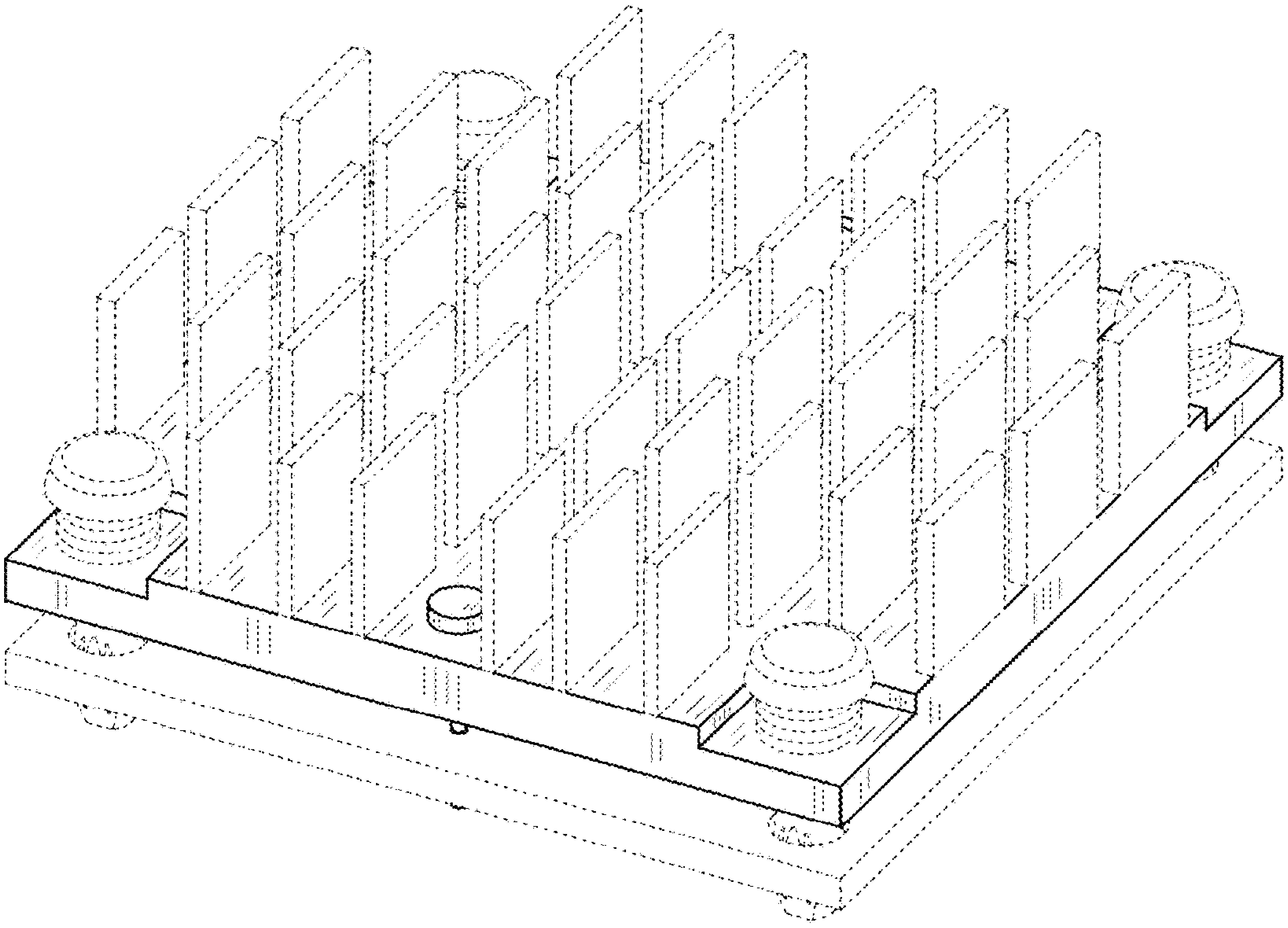

FIG. 1

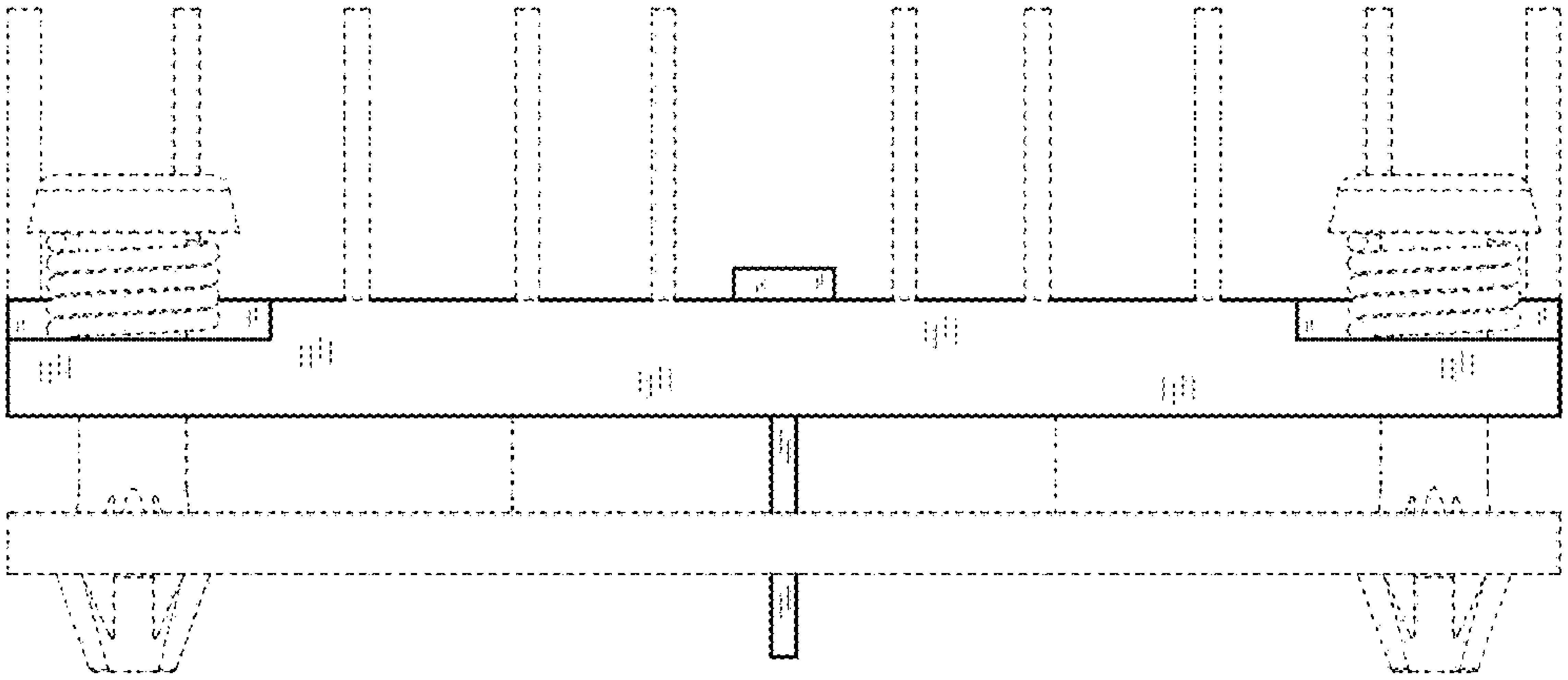

FIG. 2

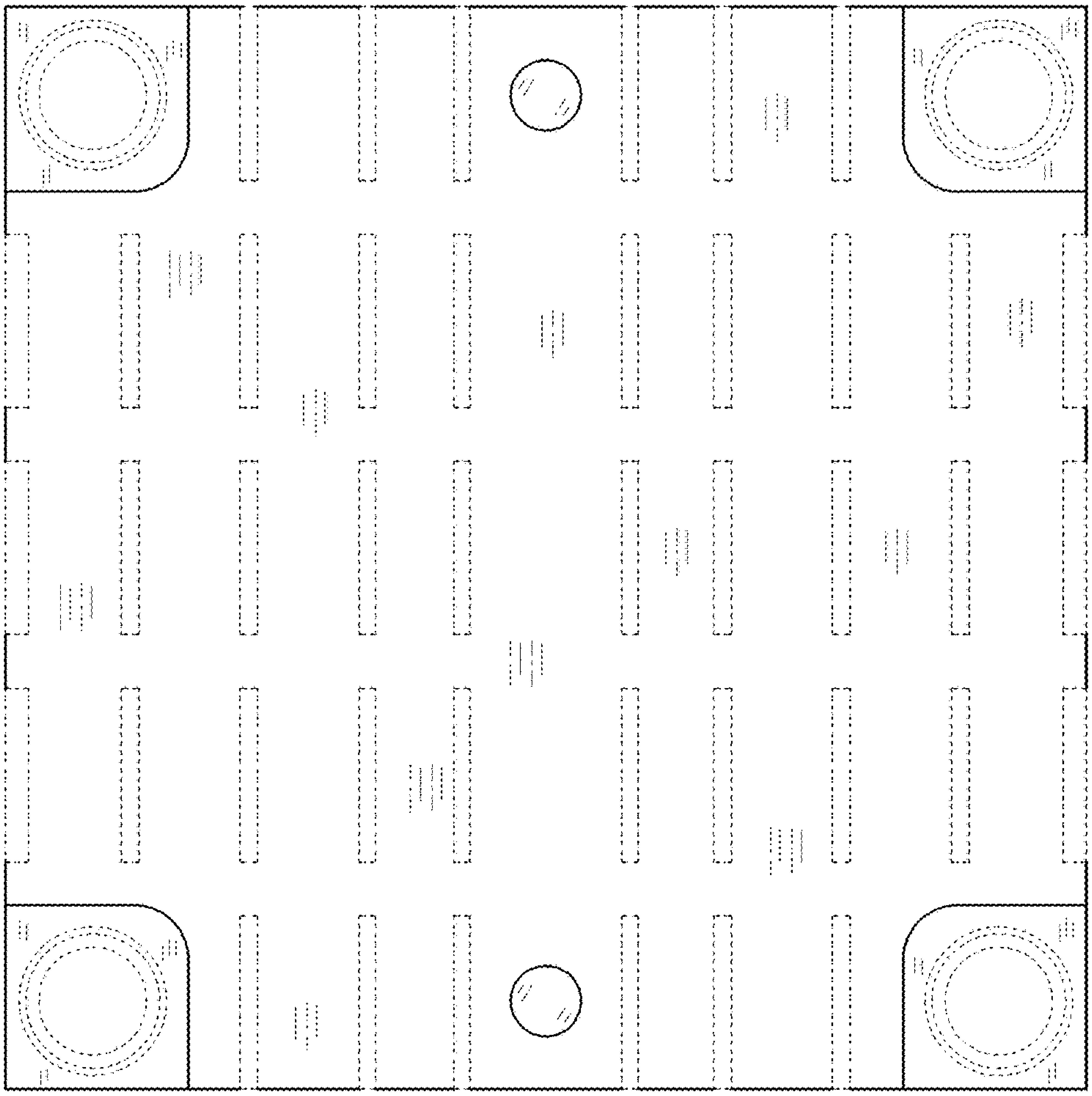

FIG. 3

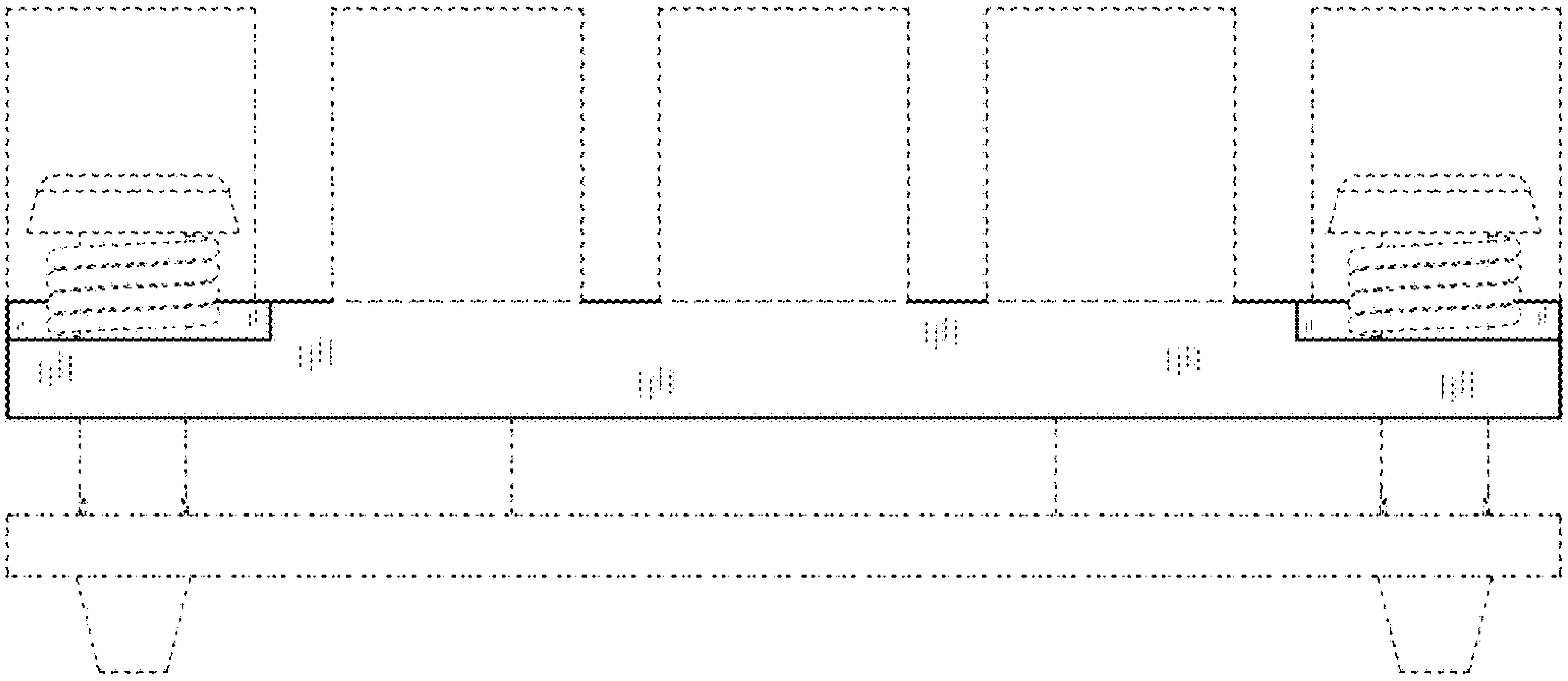

FIG. 4

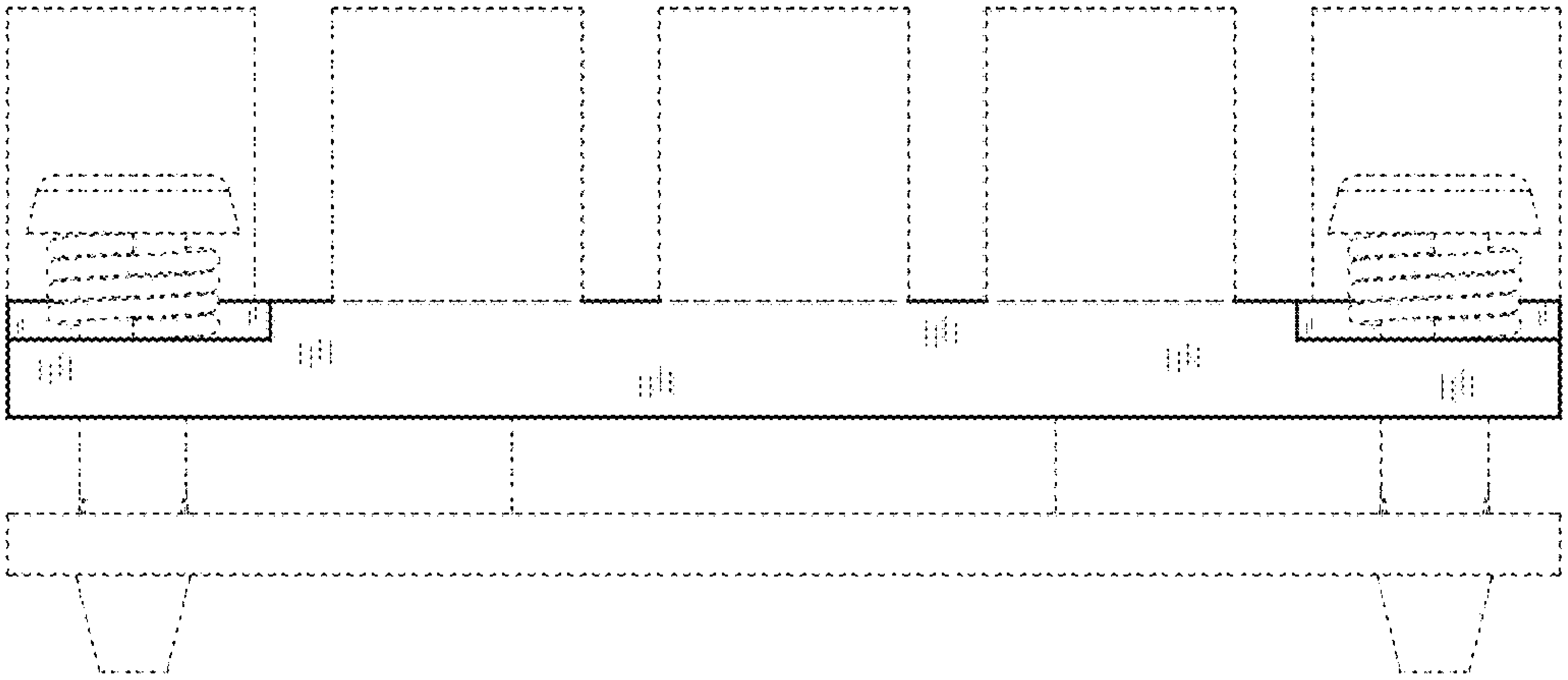

FIG. 5

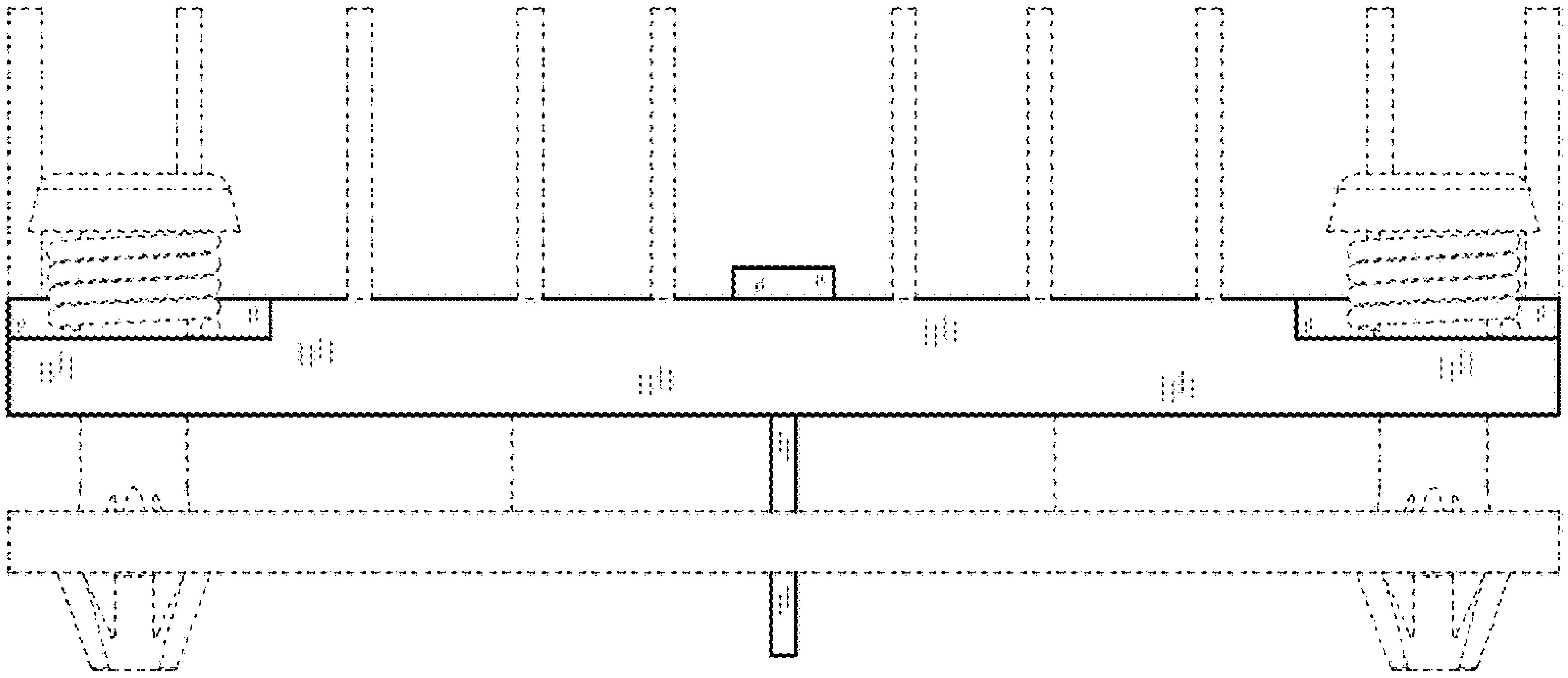

FIG. 6

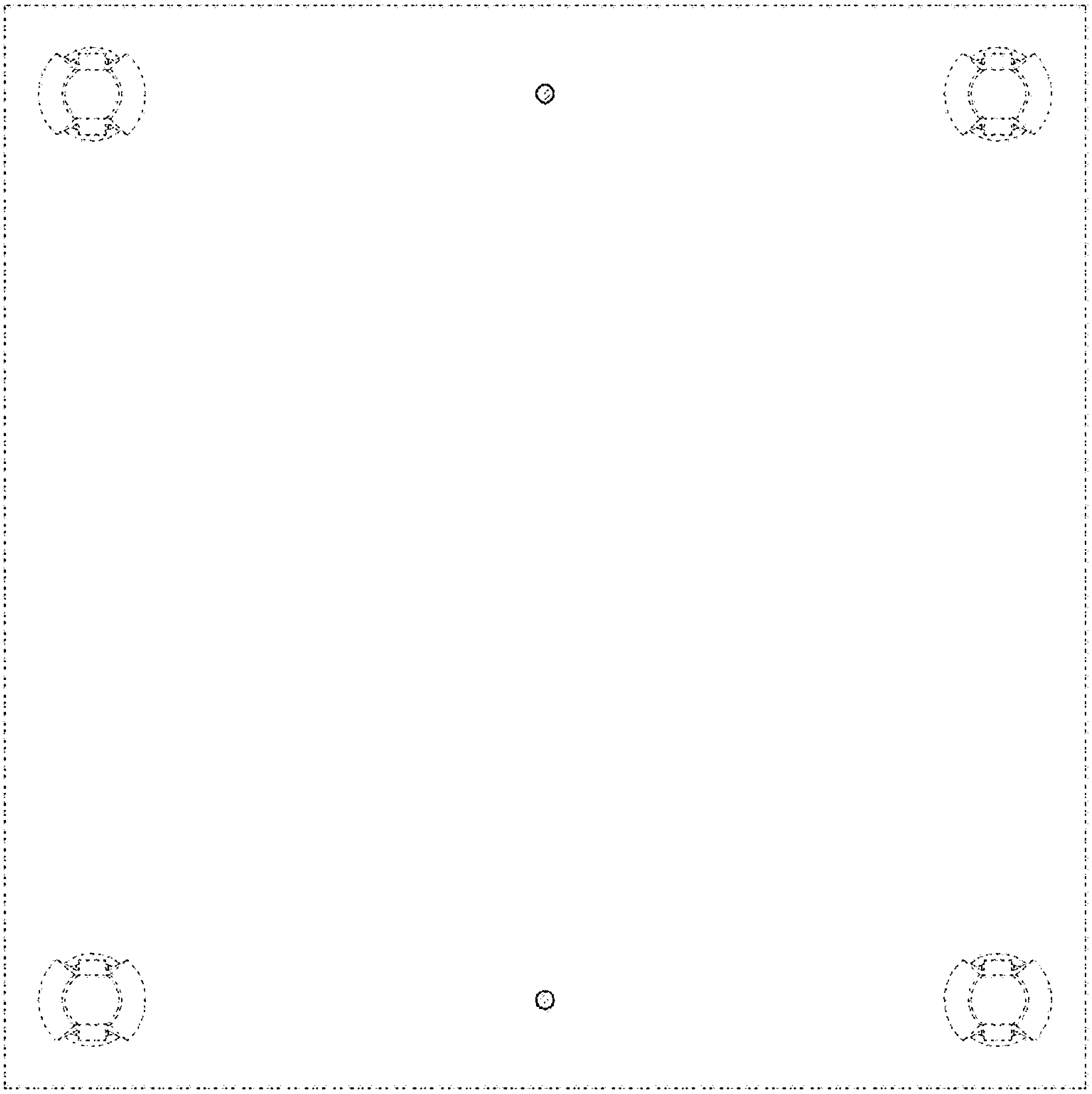

FIG. 7